Single Inverter

The NL17SZ04E is an inverter in three tiny footprint packages. The device performs much as LCX multi–gate products in speed and drive.

Features

- Tiny SOT-353 Package
- 24 mA Sink and Source Output Capability
- Over-Voltage Tolerant Inputs and Outputs
- Chip Complexity: FETs = 20
- Designed for 1.65 V to 5.5 V V_{CC} Operation
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

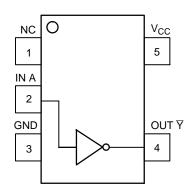


Figure 1. Pinout (Top View)

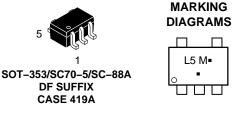






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- L5 = Specific Device Marking
- M = Date Code*
- = Pb–Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

PIN ASSIGNMENT

Pin	Function
1	NC
2	IN A
3	GND
4	OUT Y
5	V _{CC}

FUNCTION TABLE

Input	Output
Α	Ŧ
L	Н
Н	L

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit	
V _{CC}	DC Supply Voltage	–0.5 to +6.5	V	
VI	DC Input Voltage	–0.5 to +6.5	V	
V _O	DC Output Voltage Active Mode, High or Low State (Note 1 Power–Down Mode (V _{CC} = 0 V		V	
I _{IK}	DC Input Diode Current V _I < GN	D –50	mA	
I _{OK}	DC Output Diode Current V _O < GN	D –50	mA	
Ι _Ο	DC Output Sink Current	±50	mA	
I _{CC}	DC Supply Current per Supply Pin	±100	mA	
I _{GND}	DC Ground Current per Supply Pin	±100	mA	
T _{STG}	Storage Temperature Range	-65 to +150	°C	
ΤL	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C	
TJ	Junction Temperature Under Bias	+ 150	°C	
θ_{JA}	Thermal Resistance (Note 2) 350	°C/W	
PD	Power Dissipation in Still Air at 85°C	186	mW	
MSL	Moisture Sensitivity	Level 1		
F _R	Flammability Rating Oxygen Index: 28 to 3	4 UL 94 V–0 @ 0.125 in		
ESD	ESD Classification Human Body Model (Note 3 Charged Device Model (Note 4	,	V	
I _{LATCHUP}	Latchup Performance Above V _{CC} and Below GND at 125°C (Note 5)	±100	mA	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
1. IO absolute maximum rating must be observed.
2. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
3. Tested to EIA/JESD22-A114-A, rated to EIA/JESD22-A114-B.

4. Tested to JESD22-C101-A.

5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter			Max	Unit
V _{CC}	DC Supply Voltage	oltage Operating Data Retention		5.5 5.5	V
V _{IN}	DC Input Voltage		0	5.5	V
Vout	DC Output Voltage	(High or Low State) (V _{CC} = 0 V)	0 0	V _{CC} 5.5	V
V _{OUT}	DC Output Voltage (SOT-953 Package) (High or Low State)		0	V _{CC}	V
T _A	Operating Temperature Range		-55	+125	°C
t _r , t _f	Input Rise and Fall Time	$\begin{array}{l} {\sf V}_{CC} = 2.5 \; {\sf V} \pm 0.2 \; {\sf V} \\ {\sf V}_{CC} = 3.0 \; {\sf V} \pm 0.3 \; {\sf V} \\ {\sf V}_{CC} = 5.0 \; {\sf V} \pm 0.5 \; {\sf V} \end{array}$	0 0 0	20 10 5	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

	Parameter		V _{cc}	T _A = 25°C			$-55^\circ C \leq T_A \leq 125^\circ C$		
Symbol		Condition	(V)	Min	Тур	Max	Min	Max	Unit
V _{IH}	High-Level Input Voltage		1.65 to 1.95 2.3 to 5.5	0.75 V _{CC} 0.7 V _{CC}			0.75 V _{CC} 0.7 V _{CC}		V
VIL	Low-Level Input Voltage		1.65 to 1.95 2.3 to 5.5			0.25 V _{CC} 0.3 V _{CC}		0.25 V _{CC} 0.3 V _{CC}	V
V _{OH}	High-Level Output Voltage	I _{OH} = -100 μA	1.65 to 5.5	V _{CC} – 0.1	V _{CC}		V _{CC} – 0.1		V
	$V_{IN} = V_{IL}$	I _{OH} = -4 mA	1.65	1.29	1.52		1.29		
		I _{OH} = -8 mA	2.3	1.9	2.1		1.9		
		$I_{OH} = -12 \text{ mA}$	2.7	2.2	2.4		2.2		
		I _{OH} = -16 mA	3.0	2.4	2.7		2.4		-
		I _{OH} = -24 mA	3.0	2.3	2.5		2.3		
		I _{OH} = -32 mA	4.5	3.8	4.0		3.8		
V _{OL}	Low-Level Output Voltage V _{IN} = V _{IH}	I _{OL} = 100 μA	1.65 to 5.5		0.0	0.1		0.1	V
		I _{OH} = 4 mA	1.65		0.08	0.24		0.24	
		I _{OL} = 8 mA	2.3		0.20	0.3		0.3	
		I _{OL} = 12 mA	2.7		0.22	0.4		0.4	
		I _{OL} = 16 mA	3.0		0.28	0.4		0.4	
		I _{OL} = 24 mA	3.0		0.38	0.55		0.55	
		I _{OL} = 32 mA	4.5		0.42	0.55		0.55	
I _{IN}	Input Leakage Current	V _{IN} = 5.5 V or GND	1.65 to 5.5		±0.1			±1.0	μA
I _{OFF}	Power Off Leakage Current	V _{IN} = 5.5 V or V _{OUT} = 5.5 V	0			1		10	μA
I _{CC}	Quiescent Supply Current	V _{IN} = 5.5 V or GND	5.5			1		10	μA

				Т	_A = 25°C	;	–55°C ≤ T	_A ≤125°C	
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit
t _{PLH} t _{PHL}	Propagation Delay (Figure 3 and 4)	$R_L = 1 M\Omega$, $C_L = 15 pF$	1.65 1.8		5.3 4.4	11.4 9.5		12.0 10.0	ns
		$R_L = 1 M\Omega, C_L = 15 pF$	2.5 ± 0.2		3.5	6.5		7.0	
		$R_L = 1 M\Omega, C_L = 15 pF$	3.3 ± 0.3		2.1	4.5		4.7	
		$R_L = 500 \ \Omega, \ C_L = 50 \ pF$			2.9	5.5		5.2	
		$R_L = 1 M\Omega, C_L = 15 pF$	5.0 ± 0.5		1.8	3.9		4.1	
		R_L = 500 Ω , C_L = 50 pF			2.4	4.3		4.5	

AC ELECTRICAL CHARACTERISTICS t_{R} = t_{F} = 2.5 ns

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance	V_{CC} = 5.5 V, V_{I} = 0 V or V_{CC}	>2.5	pF
C _{PD}	Power Dissipation Capacitance (Note 6)	10 MHz, V_{CC} = 3.3 V, V_I = 0 V or V_{CC} 10 MHz, V_{CC} = 5.5 V, V_I = 0 V or V_{CC}	9 11	pF

6. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no–load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

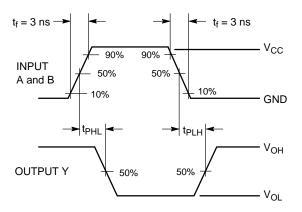
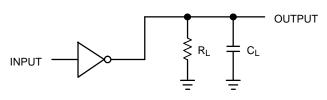


Figure 3. Switching Waveform



A 1–MHz square input wave is recommended for propagation delay tests.

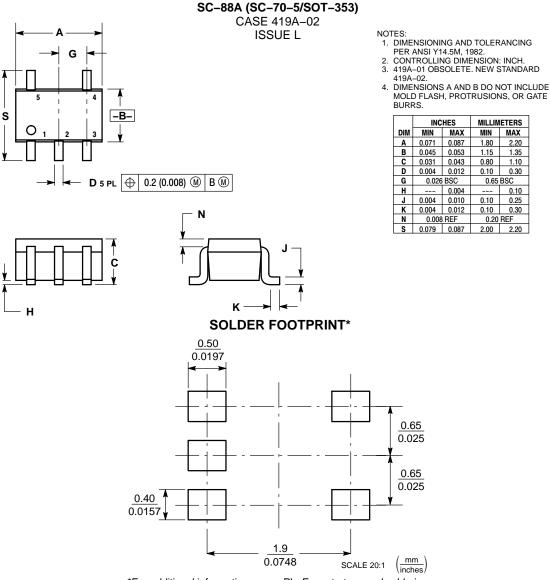


ORDERING INFORMATION

Device	Package	Shipping [†]
NL17SZ04EDFT2G	SC-88A/SOT-353/SC-70-5 (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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MILLIMETERS

MIN MAX

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0.10 0.25

0.10 0.30

0.20 REF

2.00 2 20

2.20

1.35

1.10 0.10 0.30

0.10

1.80

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